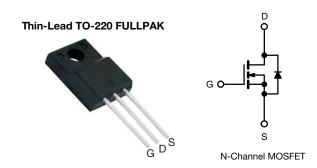


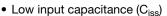
E Series Power MOSFET



PRODUCT SUMMA	RY		
V _{DS} (V) at T _J max.	550)	
$R_{DS(on)}$ max. (Ω) at 25 °C $V_{GS} = 10 \text{ V}$ 0.145			
Q _g max. (nC)	86		
Q _{gs} (nC)	14		
Q _{gd} (nC)	25		
Configuration	Sing	le	

FEATURES







- Reduced switching and conduction losses
- Low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATONS

- Hard switched topologies
- Power factor correction power supplies (PFC)
- Switch mode power supplies (SMPS)
- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA25N50E-E3

ABSOLUTE MAXIMUM RATINGS ($T_{\rm C}$	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	500	V		
Gate-Source Voltage		V_{GS}	± 30	7 v		
Continuous Drain Current (T = 150 °C) 6	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		26		
Continuous Drain Current (T _J = 150 °C) ^e	V _{GS} at 10 V	T _C = 100 °C	I _D	16	Α	
Pulsed Drain Current ^a			I _{DM}	50		
Linear Derating Factor				0.2	W/°C	
Single Pulse Avalanche Energy b		E _{AS}	273	mJ		
Maximum Power Dissipation			P_{D}	35	W	
Operating Junction and Storage Temperature Range	Э		T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	$V_{DS} = 0 \text{ V to } 80 \text{ % } V_{DS}$		d) //dt 65		V/ns	
Reverse Diode dV/dt ^d			dV/dt	25	V/IIS	
Soldering Recommendations (Peak temperature) ^c	for	10 s		300	°C	
Mounting Torque	M3 s	screw		0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4.4 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.
- e. Limited by maximum junction temperature.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.6	C/VV



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SPECIFICATIONS (T _J = 25 °C, u	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	01111202	1 .20		'''''	1	1000	0
Drain-Source Breakdown Voltage	V _{DS}	Voc	= 0 V, I _D = 250 μA	500	T _	l <u>-</u>	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$		e to 25 °C, I _D = 1 mA	-	0.59	_	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	-	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V/ U
date-Source Threshold Voltage (N)	V GS(th)		V _{GS} = ± 20 V	-	_	± 100	nA
Gate-Source Leakage	I_{GSS}		$V_{GS} = \pm 30 \text{ V}$	_		± 100	μA
			= 500 V, V _{GS} = 0 V	_	_	1	μΛ
Zero Gate Voltage Drain Current	I_{DSS}		$V_1 = 0.00 \text{ V}, V_{GS} = 0.00 \text{ V}$ $V_2 = 0.00 \text{ V}, T_J = 125 \text{ °C}$	_		25	μΑ
Drain-Source On-State Resistance	R-ac x	$V_{DS} = 400 \text{ V}$ $V_{GS} = 10 \text{ V}$	I _D = 12 A	_	0.125	0.145	Ω
Forward Transconductance	R _{DS(on)}		= 30 V, I _D = 12 A	_	6.6	0.145	S
Dynamic Dynamic	9fs	VDS	= 30 V, ID = 12 A	_	0.0	_	
•	C _{iss}	<u> </u>	V 0.V		1980	l -	I
Input Capacitance		V _{GS} = 0 V,		_	105	-	
Output Capacitance	Coss	4	V _{DS} = 100 V,		8	-	-
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	8	-	pF
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	105	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$	V _{DS} = 0 V	7 to 400 V, V _{GS} = 0 V	-	285	-	
Total Gate Charge	Qg			-	57	86	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 12 A, V_{DS} = 400 V$	=	14	-	nC
Gate-Drain Charge	Q _{gd}			-	25	-	
Turn-On Delay Time	t _{d(on)}			-	19	38	
Rise Time	t _r	V _{DD} = 400 V, I _D = 12 A		-	36	72	1
Turn-Off Delay Time	t _{d(off)}		$R_g = 9.1 \Omega$, $V_{GS} = 10 V$		57	86	ns
Fall Time	t _f			-	29	58	1
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.56	-	Ω
Drain-Source Body Diode Characteristic							
Continuous Source-Drain Diode Current	Is	MOSFET sym	MOSFET symbol showing the		-	12	
Pulsed Diode Forward Current	I _{SM}	integral revers		-	-	50	A
Diode Forward Voltage	V_{SD}	T _J = 25 °C	s, I _S = 16.5 A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}			-	338	-	ns
Reverse Recovery Charge	Q _{rr}	TJ	= 25 °C, $I_F = I_S$, 100 A/ μ s, $V_B = 25 V$	-	5.3	-	μC
Reverse Recovery Current	I _{RRM}	di/dt =	100 AV µS, VR = 20 V	-	29	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

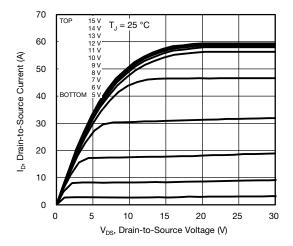


Fig. 1 - Typical Output Characteristics

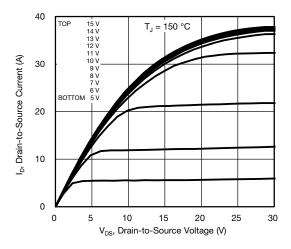


Fig. 2 - Typical Output Characteristics

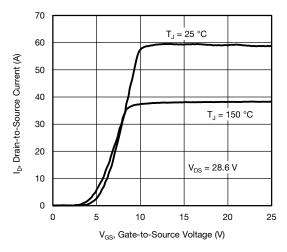


Fig. 3 - Typical Transfer Characteristics

S16-1601-Rev. D, 15-Aug-16

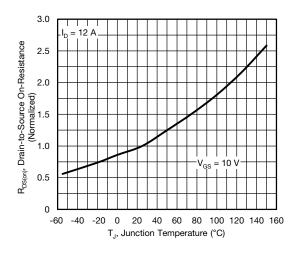


Fig. 4 - Normalized On-Resistance vs. Temperature

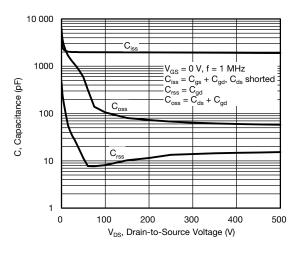


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

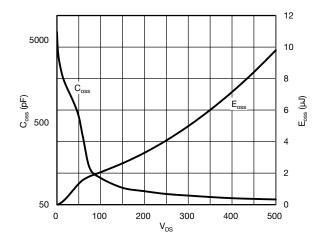


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}



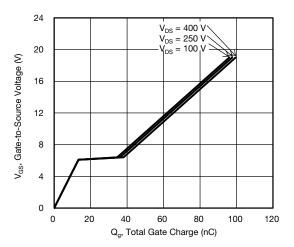


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

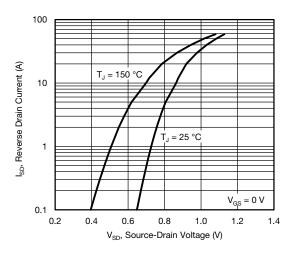


Fig. 8 - Typical Source-Drain Diode Forward Voltage

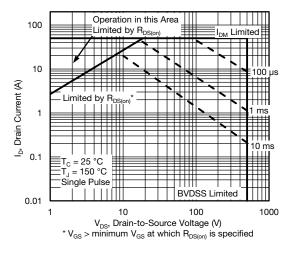


Fig. 9 - Maximum Safe Operating Area

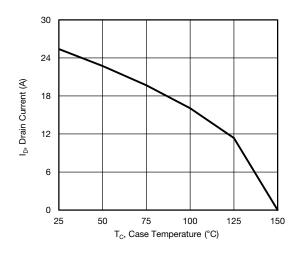


Fig. 10 - Maximum Drain Current vs. Case Temperature

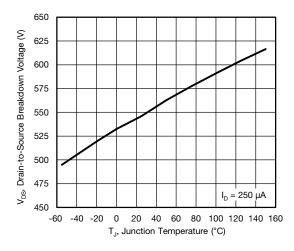


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



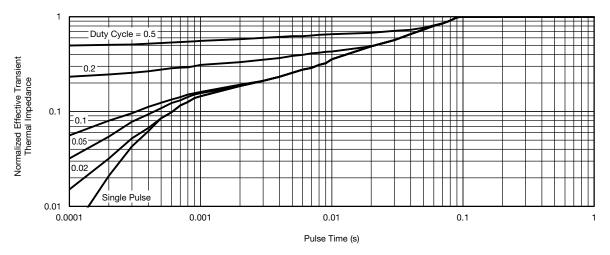


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

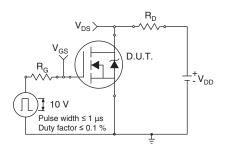


Fig. 13 - Switching Time Test Circuit

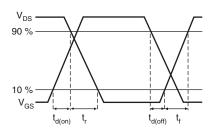


Fig. 14 - Switching Time Waveforms

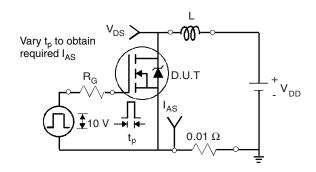


Fig. 15 - Unclamped Inductive Test Circuit

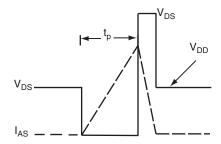


Fig. 16 - Unclamped Inductive Waveforms

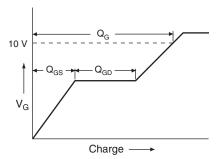


Fig. 17 - Basic Gate Charge Waveform

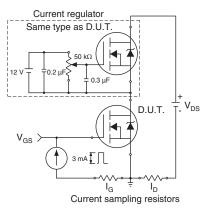
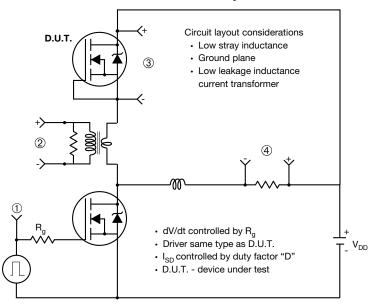


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



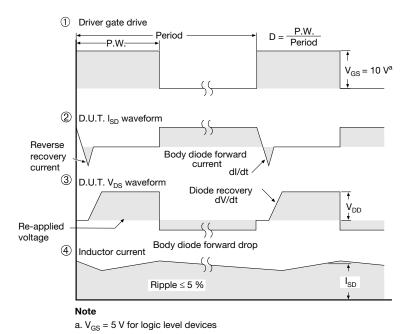


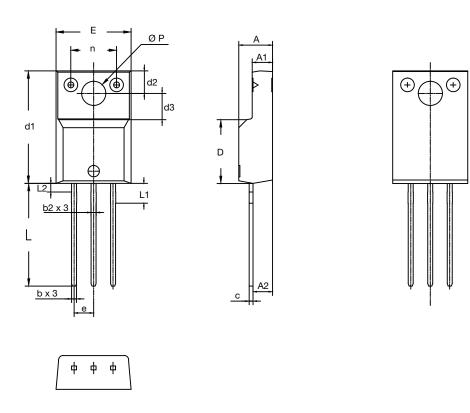
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead



		DIMEN	ISIONS	
SYMBOL	MILLIM	METERS	INCH	ES
	MIN.	MAX.	MIN.	MAX.
Α	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.50	2.70	0.098	0.106
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.40	3.60	0.134	0.142
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	2.50	2.80	0.098	0.110
L2	=	1.20	-	0.047
n	6.05	6.15	0.238	0.242
ØP	3.00	3.40	0.118	0.134

Revision: 12-Sep-16 1 Document Number: 62649



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